

Amendments to the Claims

Claim 1 (currently amended) An electronic component,
comprising:

a semiconductor chip having an active upper side with
integrated circuits, a passive rear side, and side border
regions;

said rear side and said side border regions of said
semiconductor chip being outer package sides;

AI . said rear side having corner regions and edge regions; and

at least said corner regions of said rear side, said edge
regions of said rear side, and said side border regions of
said semiconductor chip having a plastic coating with a
thickness ~~in a micrometer range~~ between 0.5 μ m and 50 μ m.

Claim 2 (original) The electronic component according to claim
1, wherein said rear side of said semiconductor chip is
completely covered by said plastic coating.

Claim 3 (currently amended) The electronic component according
to claim 1 wherein said plastic coating has a state, selected
from the group consisting of a softened state and a melted
state, ~~that~~ said plastic coating does not wet surfaces of

other solid plastic materials and but wets surfaces of semiconductor materials.

Claim 4 (original) The electronic component according to claim 1, wherein said plastic coating in the state selected from the group consisting of the softened state and the melted state is adhesive with respect to semiconductor surfaces.

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(cont)
Claim 5 (original) The electronic component according to claim 1, wherein said plastic coating includes a material selected from the group consisting of a polymer and a copolymer.

Claim 6 (original) The electronic component according to claim 1, wherein said plastic coating includes a thermoplastic.

Claim 7 (original) The electronic component according to claim 1, wherein said plastic coating includes a material selected from the group consisting of a colophony, a disproportionated colophony and a esterified colophony.

Claim 8 (original) The electronic component according to claim 1, wherein said plastic coating includes a phthalate resin.

Claim 9 (original) The electronic component according to claim 1, wherein said plastic coating includes a dimethyl glycol phthalate.

Claim 10 (original) The electronic component according to claim 1, wherein said plastic coating includes color pigments.

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(cont)
Claim 11 (original) The electronic component according to claim 1, wherein said semiconductor chip includes silicon.

Claim 12 (original) The electronic component according to claim 1, wherein said semiconductor chip has a crystal orientation of <100>.

Claims 13-27 (withdrawn)

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Claim 28 (new) The electronic component according to claim 1, wherein said plastic coating has a thickness below 15 μm .
